NOTES:
1. Bake per manufacturer instructions lower left corner of this document.
2. Samtec connectors are mounted opposite of the rigid side, DB Positronic connector is mounted from the rigid or stiffener side.
3. Solder using lead free solder.
4. Use fixtures TRNT-EL-11-0011 to support areas for surface mounted connectors, item #3, to ensure flatness and proper alignment. Surface mount connectors should be installed and soldered first.
5. To ensure proper alignment and engagement of the DB connector pins, have mating connector attached during soldering.

MANUFACTURER BAKING INSTRUCTIONS
CIREXX

Prior to any thermal exposure please follow the recommendations below for all flex and rigid flex circuit boards.

Bake all multilayer boards to high temperature exposure associated with any soldering process, boards are generally baked at 250 °C (120 °C) for three to ten hours, depending on the board thickness and layer count.

Please follow suggested baking guideline listed below:

- <30 mils, bake for 3 hours
- 30-60 mils, bake for 4 hours
- 60-90 mils, bake for 6 hours
- >120 mils, bake for 10 hours

Baking removes any moisture that has absorbed from the atmosphere as well as during processing. Polyimide films absorb moisture quickly, therefore soldering, wave, IR or vapor phase should be done within 30 minutes after baking. Otherwise, store board in a dry box or sealed plastic bag until ready for soldering.

Vacuum ovens are also used to remove water. Lower temperatures 150-175 °C (65-80 °C) can be used. This method also prevents the amount of oxidation of exposed copper pads.

ASSEMBLY CONNECTOR MOUNTING